

BRS:
BRS:
Pending
Active
L2: (2) 09/844246
L6: (6075284) "6117710" "6630728" "6060778".pn. "20030001285" "20040026773" ("6075284")
L4: (1738404) insulat\$4 dielectric
L5: (13541) exposed adj2 contact
L6: (725257) covering
L7: (113) 4 with 5 with 6
L8: (27471209) (@ad @pd) < 20010718
L8: (90) 7 and 8
L10: (23196) chipsize chip adj size stack\$4 adj (chip package)
L11: (2) 9 and 10
Failed
Saved
(2251450) (encapsula\$3 encapsulation mold\$3 resin)
(14073) stack\$4 near2 ((microchip micro adj chip chip integrated adj circuit die ic semiconductor))
(2460382) (offset stagger\$3 shift\$3 zigzag\$4 align\$4 near2 angle pitch oblique\$4 incline\$4)
(12434) (leadframe lead adj frame) 0
(1218719) (leadframe lead adj frame lead)
(6841) ((offset stagger\$3 shift\$3 zigzag\$4 align\$4 near2 angle pitch oblique\$4 incline\$4))
(79) ((leadframe lead adj frame) 0)
(444) ((leadframe lead adj frame) 0)
(18011) ((offset stagger\$3 shift\$3 zigzag\$4 align\$4 near2 angle pitch oblique\$4 incline\$4))
(241) ((leadframe lead adj frame) 0)
(898) ((leadframe lead adj frame) 0)
(60) ((leadframe lead adj frame) 0)

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		<input checked="" type="checkbox"/> Highlight all hit terms initially		
"6075284" "6117710" "6630728" "6060778".pn. "20030001285" "20040026773" ("6576494" "6501184" "8429528" "6339254" "6228687" "6084058" "6088920" "6066514" "5973383" "5866953" "5815000" "5138434" "5107328".pn.				
Oct 2 2004				

U	Inventor	Document ID	Issue D/P	Title	Current C	Current X	Ref	Retrieval C	S	C	P	J	Image	Doc. D/P
1	AKRAM, S et al.	US 6226687 B	2001/05/18	Fabrication of chip-scale package involves adhering pr					P	C	C	C	C	US 6226687
2	AKRAM, S et al.	US 6088920 A	2000/07/16	Modular die socket for packaging semiconductor die, h					P	C	C	C	C	US 6088920
3	AKRAM, S et al.	US 5866953 A	1999/02/14	Heat sink for semiconductor chip of BGA, PGA, TAB, S					P	C	C	C	C	US 5866953
4	AKRAM, S et al.	JP 09197006 A	1997/07/14	Semiconductor die packing method - involves mounting					P	C	C	C	C	US 5815000
5	AKRAM, S et al.	TW 303502 A	1997/04/11	Temporary semiconductor package having dense array					P	C	C	C	C	US 6094058
6	Akram, Salman	US 6226687 B	2001/05/18	Wafer-level package and methods of fabricating	438/125	257/E21.508;			P	C	C	C	C	US 6226687
7	Akram, Salman	US 5866953 A	1999/02/14	Packaged die on PCB with heat sink encapsulant	257/790	257/687;			P	C	C	C	C	US 5866953
8	BROOKS, J M et US	6066514 A	2000/05/4	Enhancing adhesion of a semiconductor die for mold co					P	C	C	C	C	US 6066514